US00D934820S

(12) **United States Design Patent**
Okawa et al.

(10) **Patent No.: US D934,820 S**
(45) **Date of Patent: ** Nov. 2, 2021**

(54) **SEMICONDUCTOR DEVICE**

(71) Applicant: **Panasonic Intellectual Property Management Co., Ltd.**, Osaka (JP)

(72) Inventors: **Ryosuke Okawa**, Nara-ken (JP); **Toshikazu Imai**, Hyogo-ken (JP); **Kazuma Yoshida**, Kyoto-fu (JP); **Tsubasa Inoue**, Osaka-fu (JP); **Takeshi Imamura**, Kyoto-fu (JP)

(73) Assignee: **NUVOTON TECHNOLOGY CORPORATION JAPAN**, Nagaokakyo (JP)

(**) Term: **15 Years**

(21) Appl. No.: **29/710,622**

(22) Filed: **Oct. 24, 2019**

(51) **LOC (13) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/182**

(58) **Field of Classification Search**
USPC D13/182; D21/391
CPC H01L 21/00; H01L 21/02; H01L 21/4814; H01L 21/4846; H01L 21/4871; H01L 21/67144; H01L 2224/42; H01L 2224/43; H01L 2224/01; H01L 2224/08055; H01L 2224/08054; H01L 23/12; H01L 23/13; H01L 23/14; H01L 23/147; H01L 23/00; H01L 23/48; H01L 23/4926; H01L 23/495; H01L 23/49517; H01L 23/498; H01L 23/49805; H01L 23/49811; H01L 23/49861; H01L 23/49866; H01L 23/49872; H01L 23/49575; H01L 23/49579; H01L 2924/171; H01L 2924/1711; H01L 2924/1715; H01L 2924/181; H01L 2924/1811; H01L 2924/1815; H01L 2924/19042; H01L 2924/1905
See application file for complete search history.

(56) **References Cited**

U.S. PATENT DOCUMENTS

273,559	A *	3/1883	Lockwood	A63F 1/02 273/293
729,489	A *	5/1903	Cigol	A63F 1/02 273/295
1,998,526	A *	4/1935	Schubert	A63F 9/20 273/292
D142,491	S *	10/1945	Neiser	D21/391
D318,461	S *	7/1991	Hasegawa	D13/182
D319,045	S *	8/1991	Hasegawa	D13/182
D319,629	S *	9/1991	Hasegawa	D13/182
D319,814	S *	9/1991	Hasegawa	D13/182
6,307,269	B1 *	10/2001	Akiyama	H01L 24/50 257/778

(Continued)

FOREIGN PATENT DOCUMENTS

JP	D1581768	7/2017
JP	D1588125	10/2017

(Continued)

Primary Examiner — Elizabeth J Oswecki

(74) *Attorney, Agent, or Firm* — Crowell & Moring LLP

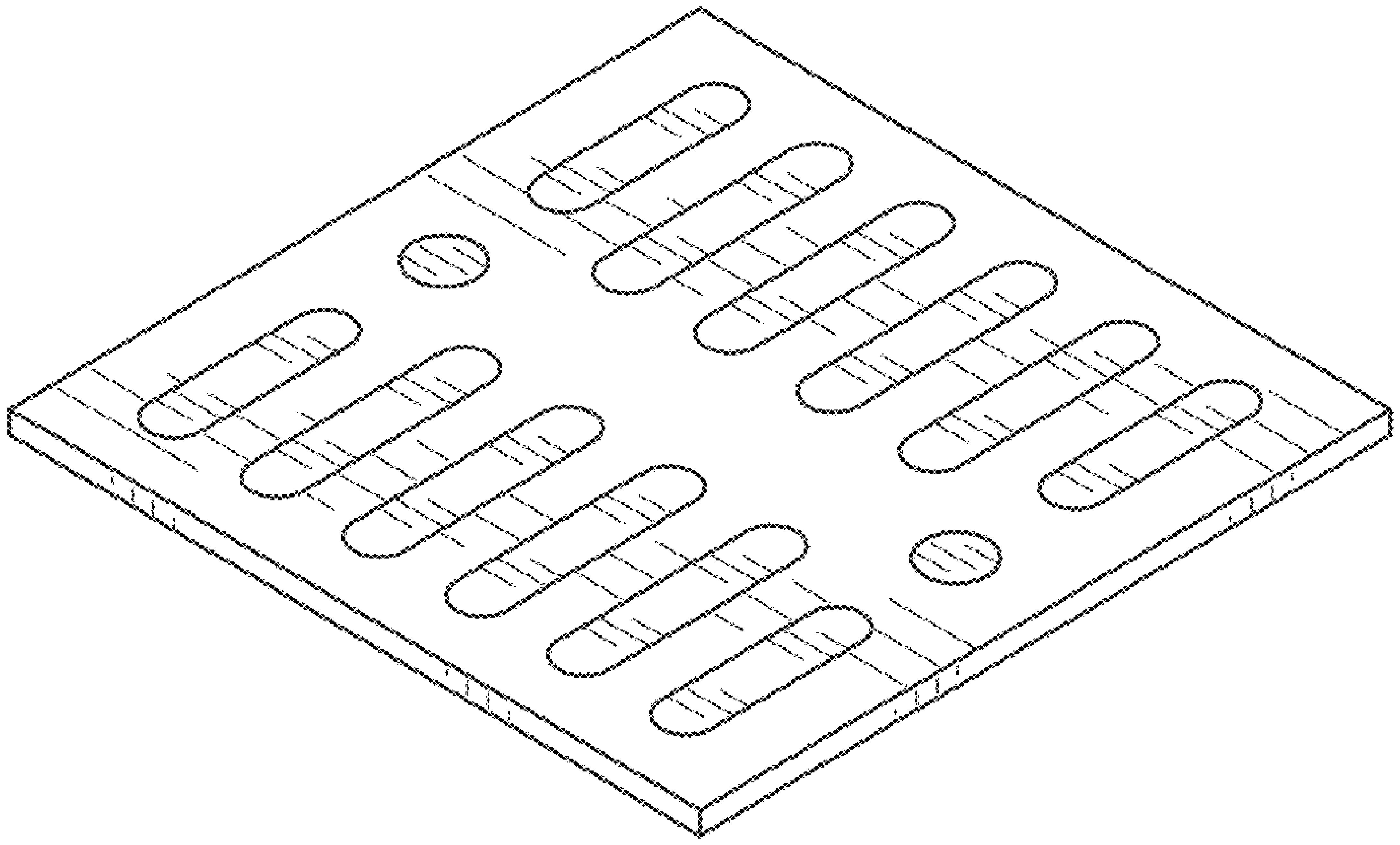
(57) **CLAIM**

The ornamental design for a semiconductor device, as shown and described.

DESCRIPTION

FIG. **1** is a perspective view of a semiconductor device showing our new design;
FIG. **2** is a front view thereof;
FIG. **3** is a rear view thereof;
FIG. **4** is a left side view thereof;
FIG. **5** is a right side view thereof;
FIG. **6** is a top view thereof; and,
FIG. **7** is a bottom view thereof.

1 Claim, 4 Drawing Sheets



(56) References Cited

U.S. PATENT DOCUMENTS

D466,093	S	*	11/2002	Ebihara	D13/182
D471,167	S	*	3/2003	Ebihara	D13/182
D487,430	S	*	3/2004	Asaka	D13/182
6,836,002	B2	*	12/2004	Chikawa	H01L 23/522 257/666
D598,380	S	*	8/2009	Kuriki	D13/133
D687,898	S	*	8/2013	Lupkas	D21/391
D691,101	S	*	10/2013	Ishizawa	D13/182
D704,155	S	*	5/2014	Chang	D13/182
D721,047	S	*	1/2015	Vinciarelli	D13/182
D730,304	S	*	5/2015	Matsumoto	D13/182
D754,083	S	*	4/2016	Vinciarelli	D13/182
D757,693	S	*	5/2016	Sudo	D14/230
D764,424	S	*	8/2016	Matsumoto	D13/182
D775,093	S	*	12/2016	Vinciarelli	D13/182
D778,850	S	*	2/2017	Matsumoto	D13/182
D797,066	S	*	9/2017	Zhang	D13/180
D813,182	S	*	3/2018	Imai	D13/182
D837,171	S	*	1/2019	Vasoya	D13/182
D850,309	S	*	6/2019	Jovanovic	D10/80
D864,882	S	*	10/2019	Sakamoto	D13/182
D864,883	S	*	10/2019	Sakamoto	D13/182
D865,690	S	*	11/2019	Sakamoto	D13/182
D902,164	S	*	11/2020	Kondo	D13/182
D904,325	S	*	12/2020	Omichi	D13/182
D904,355	S	*	12/2020	Horn	D14/230

FOREIGN PATENT DOCUMENTS

JP	D1588481	10/2017
JP	D1632160	5/2019
JP	D1632597	5/2019
JP	D1640664	9/2019
JP	D1641048	9/2019
JP	D1641049	9/2019

* cited by examiner

FIG. 1

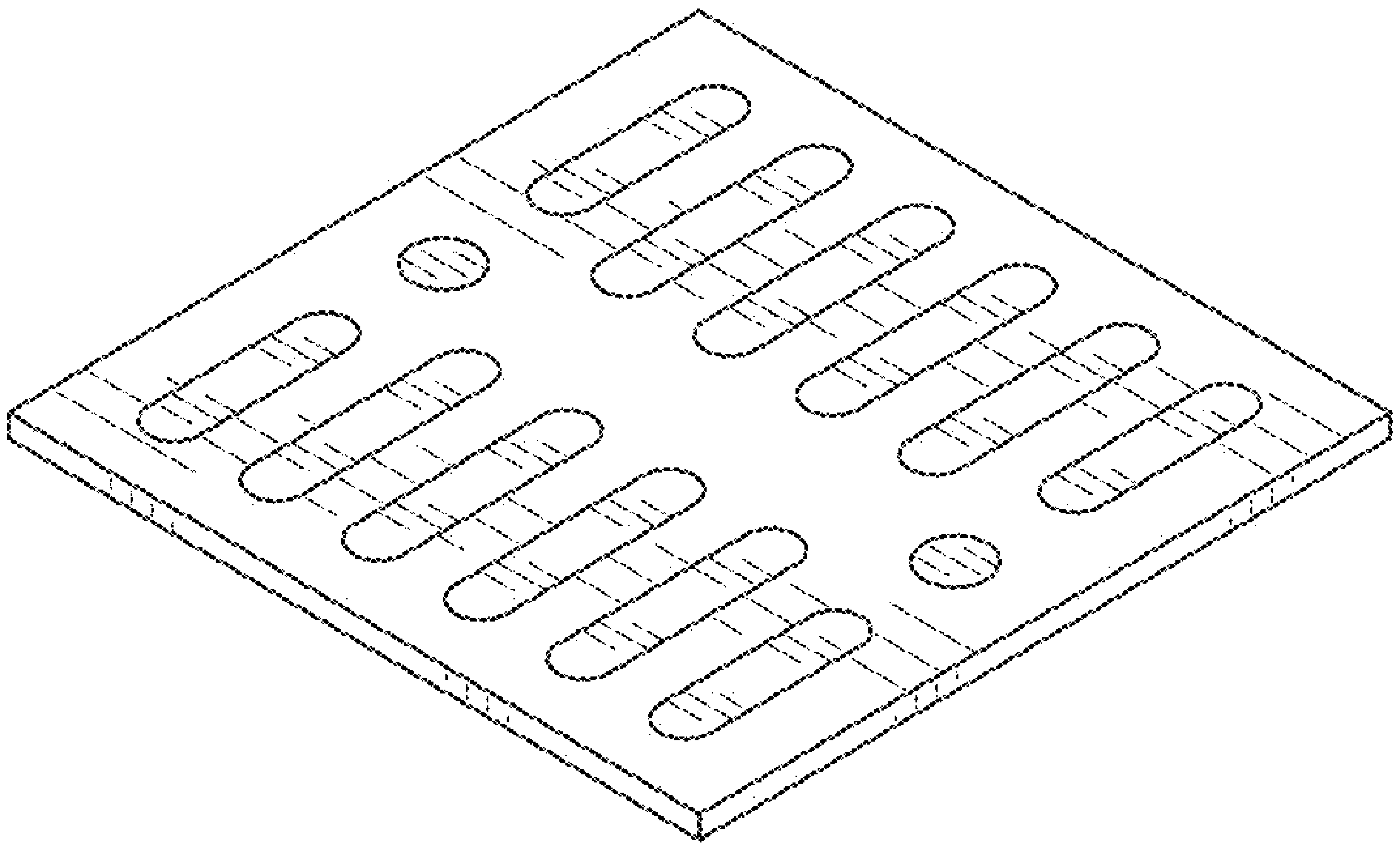


FIG. 2

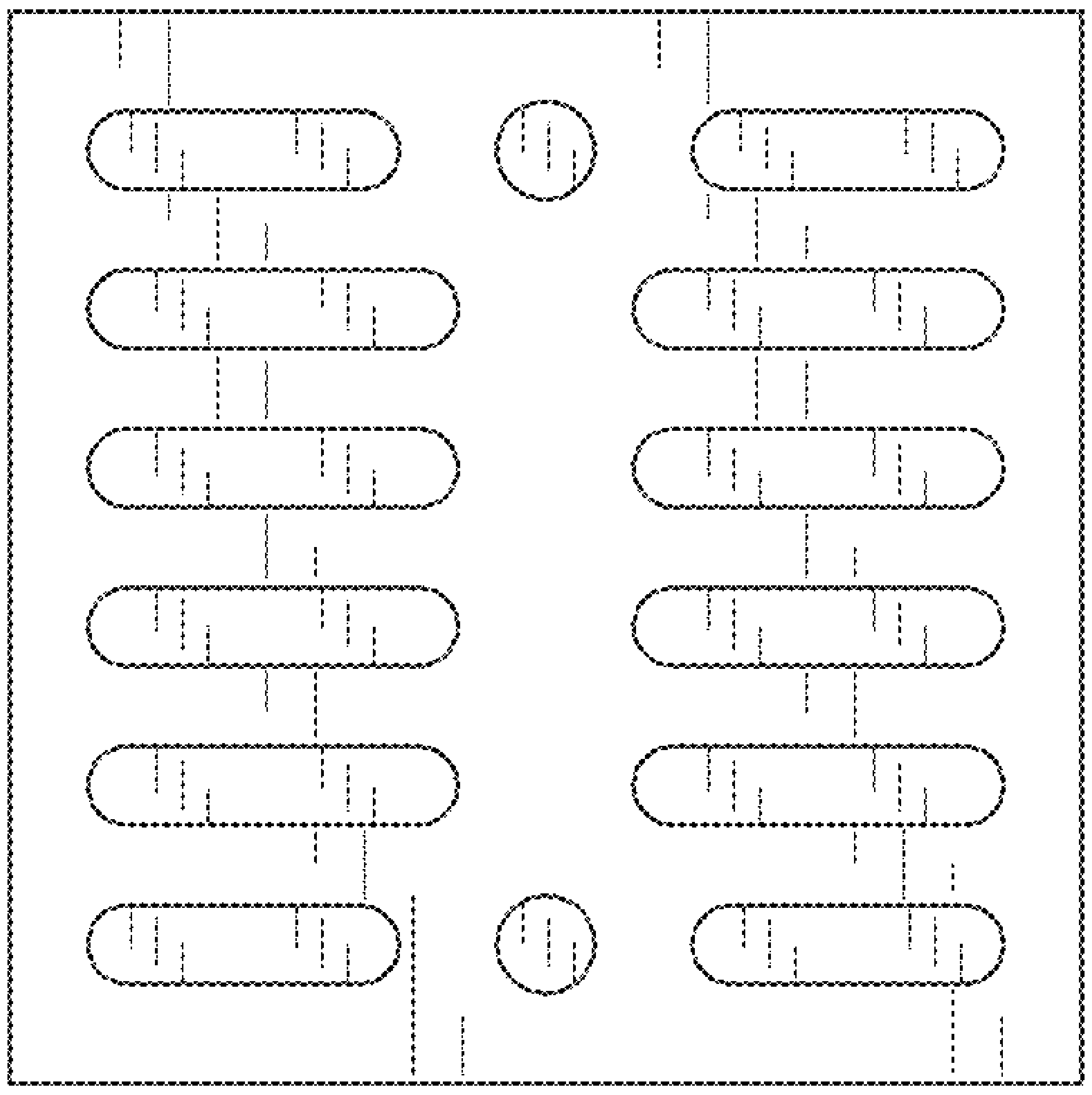


FIG. 3

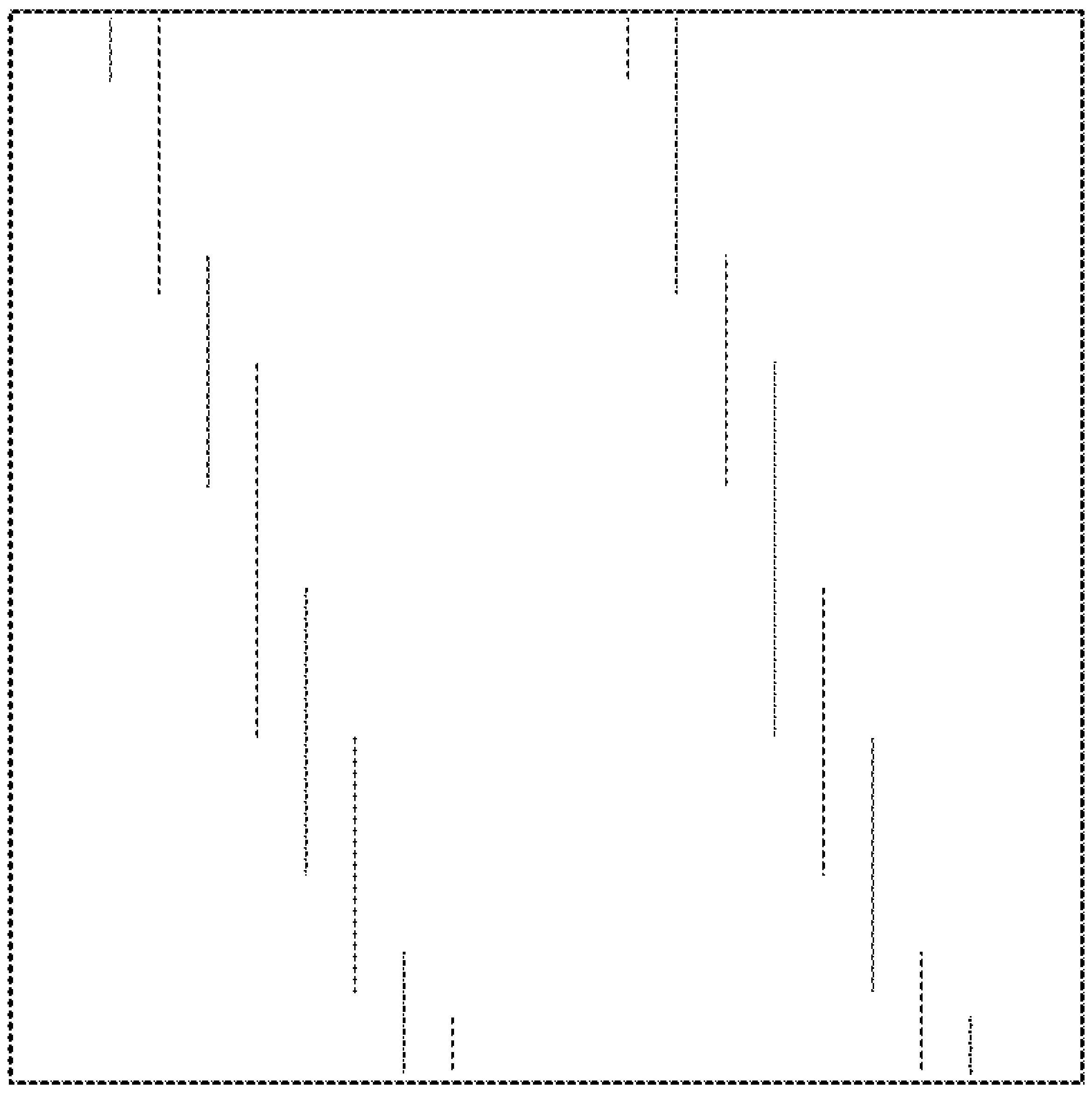


FIG. 4

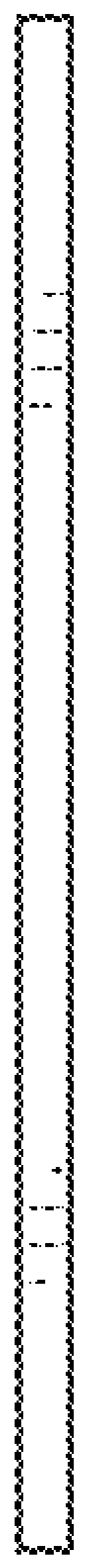


FIG. 5

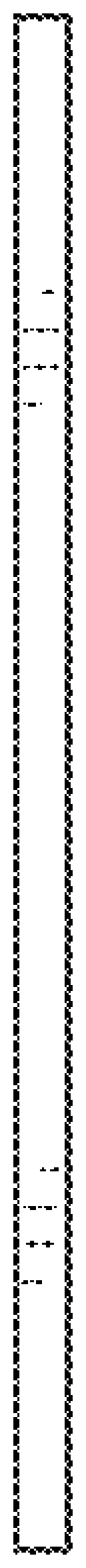


FIG. 6

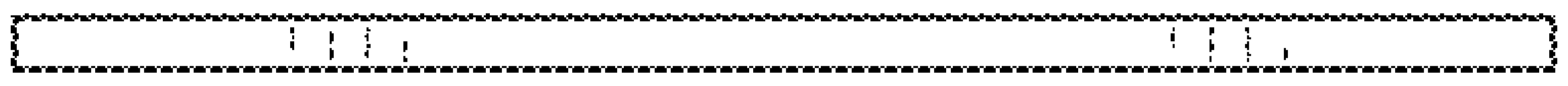


FIG. 7